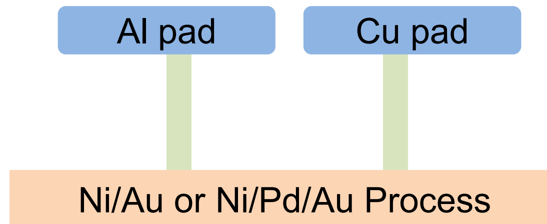
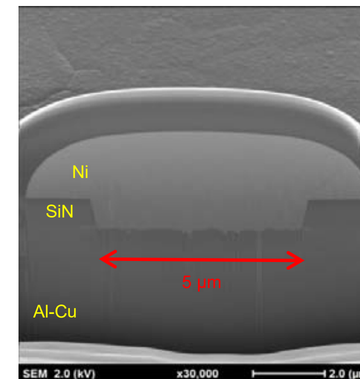
Al、Cu電極への無電解UBM形成プロセス
Electroless UBM Forming Process on Al or Cu Pad

エピタスプロセス / EPITHAS Process

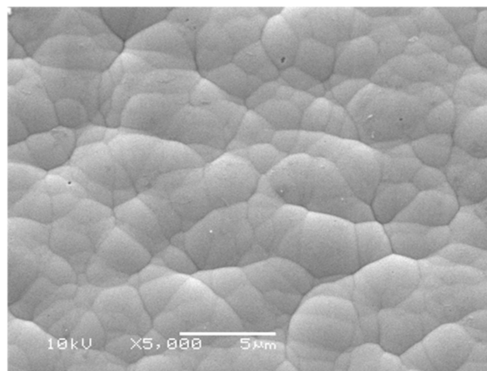
◆特長　Feature

ウェハー上のAlまたはCu電極に、はんだ接合とワイヤボンディング性に優れたUBMを形成できる
EPITHAS electroless plating process can form UBM on Al pad or Cu pad of wafer. The deposits have excellent solder joint and wire bonding ability.

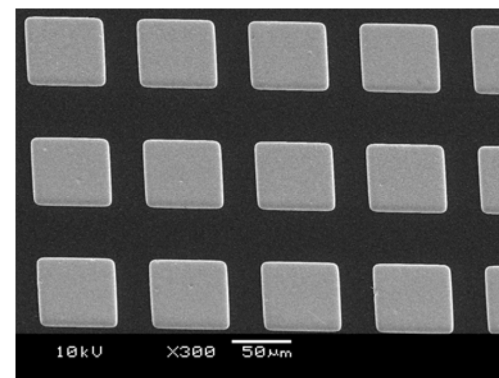




Cross-section after Ni plating on 5 µm pad



Ni surface after Au stripping SEM photo image
(ENIG process)



Ni/Au Bump SEM photo image

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